



SPECIFICATIONS:

- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500VDC.
- CONTACT RESISTANCE: 50mΩ MAX(INITIAL).
- INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
- UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
- LIFE TEST: 5,000 CYCLES MIN.
- INSERTION FORCE: INITIAL 0.30-3.0kgf ,AFTER DURABILITY 0.3kgf Min.;
- WITHDRAWAL FORCE: INITIAL 0.30-3.0 kgf, AFTER DURABILITY 0.3kgf Min.;
- AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
- AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
- MARKING: MARK "S" ON TOP OF CONNECTOR.
- PACKAGING : TAPE & REEL.
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT.
- HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA, GOLD FLASH ON SOLDER TAIL, ALL OVER Ni 50 μm
F	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	
E	TIP SPRING	1	PHOSPHOR BRONZE 0.2t	
D	RING A	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA, Nickle Sn70Zn Min. ON SOLDER AREA, ALL OVER 50μ Ni.
C	RING B	1	PHOSPHOR BRONZE 0.2t	
B	EARTH	1	PHOSPHOR BRONZE 0.2t	Nickle Sn70Zn Min. ON SOLDER AREA, ALL OVER 50μ Ni.
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

Singatron Enterprise Co., Ltd.
信亨企業股份有限公司

TITLE: 3.5Ø PHONE JACK

DWN: MARS PART NO. 2S13080-038111F

CHKD: Bruce SCALE 4:1 UNIT: mm

APVD: Lussen SIZE: A3 SHEET: 1 OF 1 REV: A

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REV	EGN NO	OR DESCRIPTION	REVISED	DATE
A	PDR NO: T130618-3A	MARS	2013.07.02	